

SEMiX[®] 33c

Trench IGBT Modules

SEMiX503GD126HDc

Features

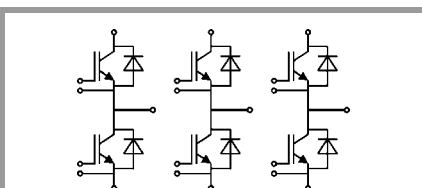
- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability
- UL recognised file no. E63532

Typical Applications*

- AC inverter drives
- UPS
- Electronic Welding

Remarks

- Case temperatur limited to $T_C=125^\circ\text{C}$ max.
- Not for new design



GD

Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
IGBT				
V_{CES}			1200	V
I_C	$T_j = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$	466	A
		$T_c = 80^\circ\text{C}$	327	A
I_{Cnom}			300	A
I_{CRM}	$I_{CRM} = 2 \times I_{Cnom}$		600	A
V_{GES}			-20 ... 20	V
t_{psc}	$V_{CC} = 600\text{ V}$	$T_j = 125^\circ\text{C}$	10	μs
	$V_{GE} \leq 20\text{ V}$			
	$V_{CES} \leq 1200\text{ V}$			
T_j			-40 ... 150	$^\circ\text{C}$
Inverse diode				
I_F	$T_j = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$	412	A
		$T_c = 80^\circ\text{C}$	284	A
I_{Fnom}			300	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$		600	A
I_{FSM}	$t_p = 10\text{ ms, sin } 180^\circ, T_j = 25^\circ\text{C}$		2000	A
T_j			-40 ... 150	$^\circ\text{C}$
Module				
$I_{t(RMS)}$			600	A
T_{stg}			-40 ... 125	$^\circ\text{C}$
V_{isol}	AC sinus 50Hz, t = 1 min		4000	V

Characteristics							
Symbol	Conditions		min.	typ.	max.	Unit	
IGBT							
$V_{CE(sat)}$	$I_C = 300\text{ A}$	$V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	1.7	2.1	V	
			$T_j = 125^\circ\text{C}$	2	2.45	V	
V_{CE0}			$T_j = 25^\circ\text{C}$	1	1.2	V	
			$T_j = 125^\circ\text{C}$	0.9	1.1	V	
r_{CE}	$V_{GE} = 15\text{ V}$			$T_j = 25^\circ\text{C}$	2.3	3.0	$\text{m}\Omega$
				$T_j = 125^\circ\text{C}$	3.7	4.5	$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE}=V_{CE}, I_C = 12\text{ mA}$		5	5.8	6.5	V	
I_{CES}	$V_{GE} = 0\text{ V}$	$V_{CE} = 1200\text{ V}$	$T_j = 25^\circ\text{C}$	0.1	0.3	mA	
			$T_j = 125^\circ\text{C}$			mA	
C_{ies}	$V_{CE} = 25\text{ V}$ $V_{GE} = 0\text{ V}$		$f = 1\text{ MHz}$	21.6		nF	
C_{oes}			$f = 1\text{ MHz}$	1.13		nF	
C_{res}			$f = 1\text{ MHz}$	0.98		nF	
Q_G	$V_{GE} = -8\text{ V...} + 15\text{ V}$			2400		nC	
R_{Gint}	$T_j = 25^\circ\text{C}$			2.50		Ω	
$t_{d(on)}$	$V_{CC} = 600\text{ V}$	$I_C = 300\text{ A}$	$T_j = 125^\circ\text{C}$	275		ns	
t_r			$T_j = 125^\circ\text{C}$	55		ns	
E_{on}	$R_{Gon} = 2.2\ \Omega$		$T_j = 125^\circ\text{C}$	28		mJ	
$t_{d(off)}$	$R_{Goff} = 2.2\ \Omega$		$T_j = 125^\circ\text{C}$	625		ns	
t_f			$T_j = 125^\circ\text{C}$	125		ns	
E_{off}			$T_j = 125^\circ\text{C}$	44		mJ	
$R_{th(j-c)}$	per IGBT				0.08	K/W	



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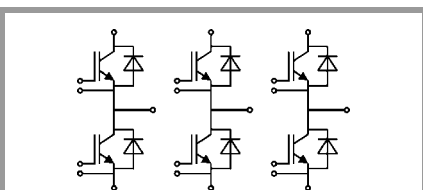
Typical Applications*

- AC inverter drives
- UPS
- Electronic Welding

Remarks

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Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse diode						
$V_F = V_{EC}$	$I_F = 300\text{ A}$ $V_{GE} = 0\text{ V}$ chip	$T_j = 25^\circ\text{C}$		1.6	1.80	V
		$T_j = 125^\circ\text{C}$		1.6	1.8	V
V_{F0}		$T_j = 25^\circ\text{C}$	0.9	1	1.1	V
		$T_j = 125^\circ\text{C}$	0.7	0.8	0.9	V
r_F		$T_j = 25^\circ\text{C}$	1.7	2.0	2.3	m Ω
		$T_j = 125^\circ\text{C}$	2.3	2.7	3.0	m Ω
I_{RRM}	$I_F = 300\text{ A}$ $di/dt_{off} = 6900\text{ A}/\mu\text{s}$	$T_j = 125^\circ\text{C}$		400		A
Q_{rr}	$V_{GE} = -15\text{ V}$	$T_j = 125^\circ\text{C}$		77		μC
E_{rr}	$V_{CC} = 600\text{ V}$	$T_j = 125^\circ\text{C}$		32.5		mJ
$R_{th(j-c)}$	per diode				0.14	K/W
Module						
L_{CE}				20		nH
$R_{CC'+EE'}$	res., terminal-chip	$T_C = 25^\circ\text{C}$		0.7		m Ω
		$T_C = 125^\circ\text{C}$		1		m Ω
$R_{th(c-s)}$	per module			0.014		K/W
M_s	to heat sink (M5)		3		5	Nm
M_t		to terminals (M6)	2.5		5	Nm
w					900	g
Temperatur Sensor						
R_{100}	$T_C=100^\circ\text{C}$ ($R_{25}=5\text{ k}\Omega$)			$493 \pm 5\%$		Ω
$B_{100/125}$	$R_{(T)}=R_{100}\exp[B_{100/125}(1/T-1/T_{100})]$; $T[\text{K}]$;			3550 $\pm 2\%$		K



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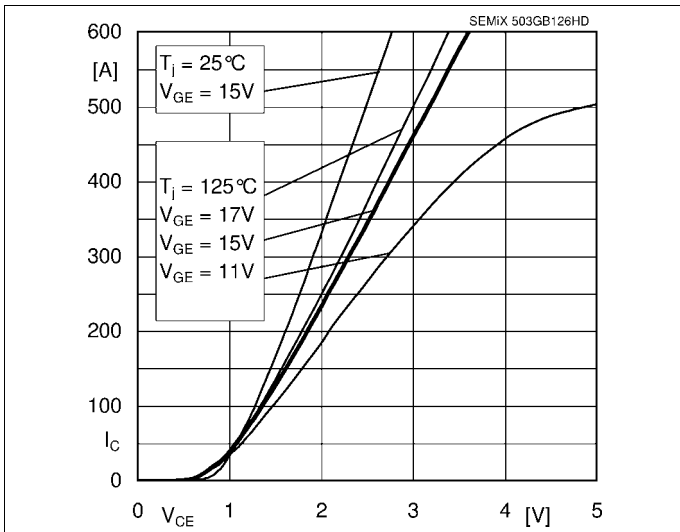


Fig. 1: Typ. output characteristic, inclusive $R_{CC'+EE'}$

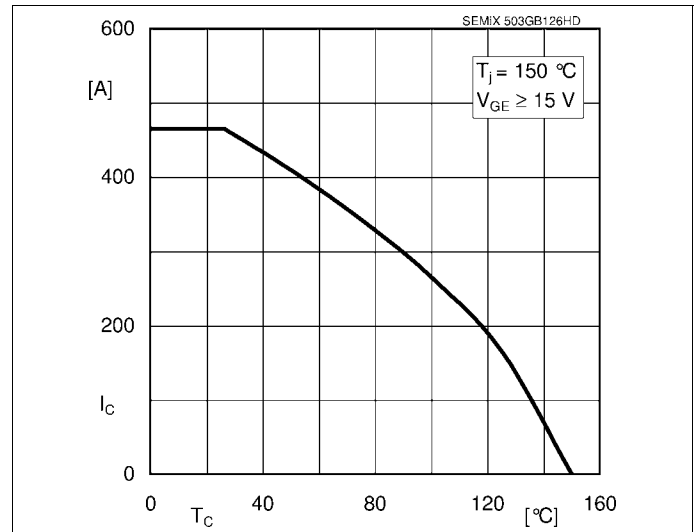


Fig. 2: Rated current vs. temperature $I_c = f(T_c)$

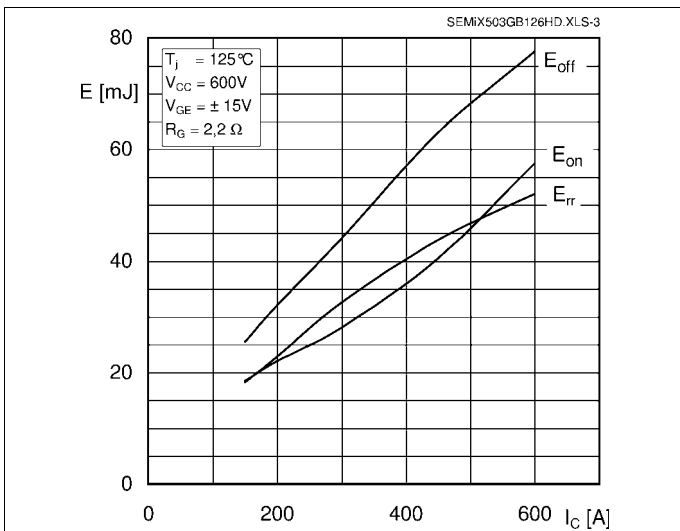


Fig. 3: Typ. turn-on /-off energy = $f(I_c)$

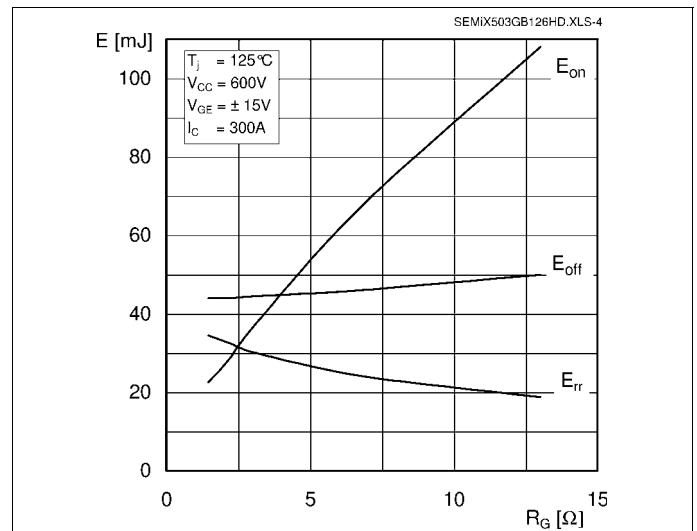


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

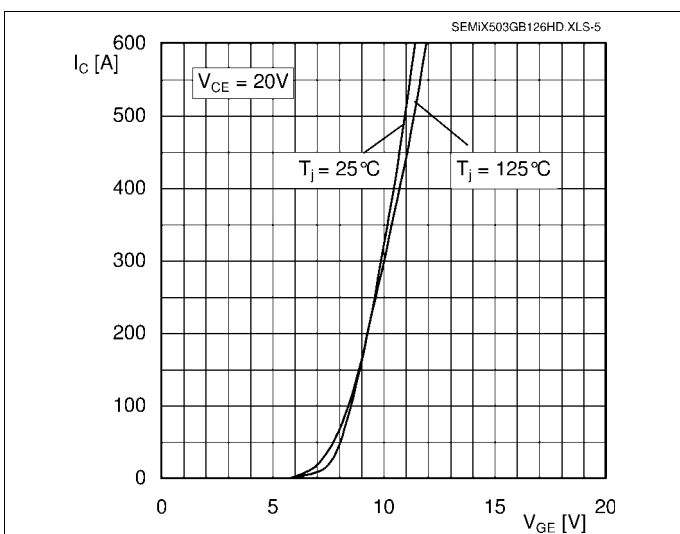


Fig. 5: Typ. transfer characteristic

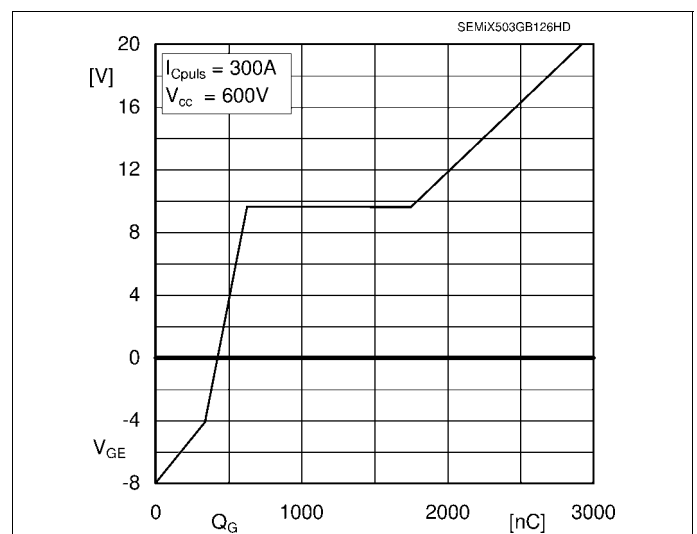


Fig. 6: Typ. gate charge characteristic

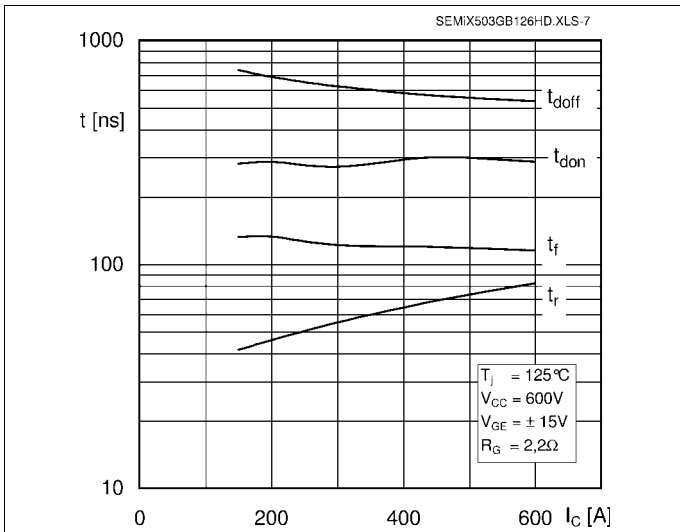


Fig. 7: Typ. switching times vs. I_C

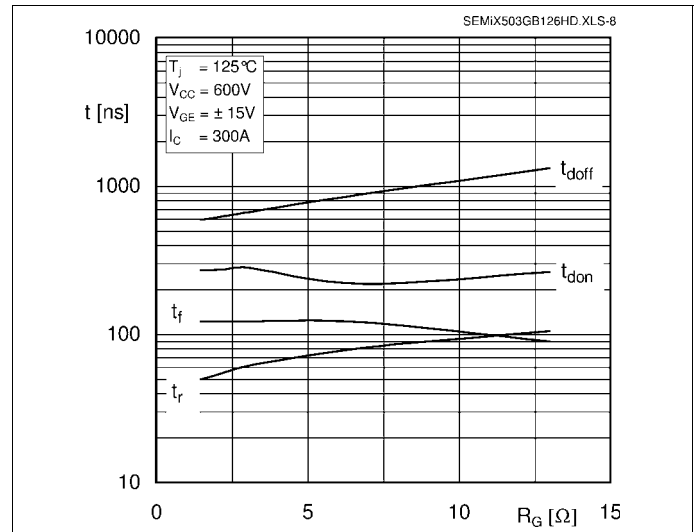


Fig. 8: Typ. switching times vs. gate resistor R_G

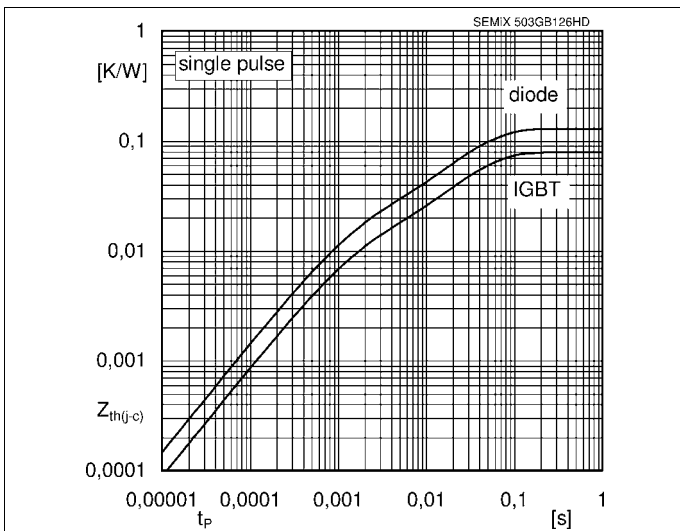


Fig. 9: Typ. transient thermal impedance

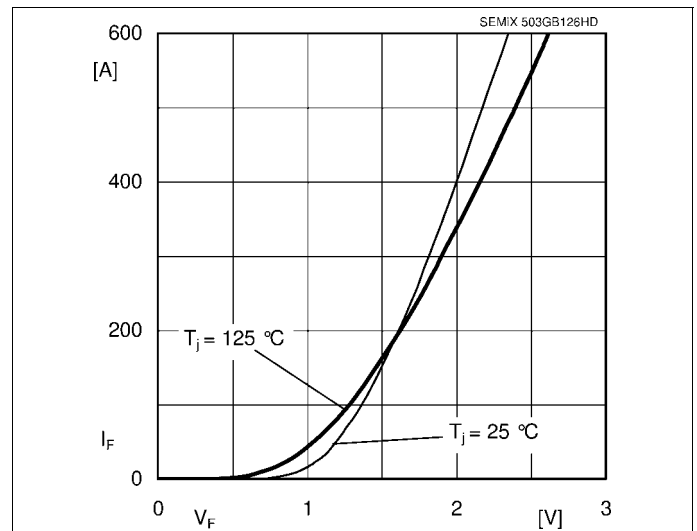


Fig. 10: Typ. CAL diode forward charact., incl. R_{CC+EE}

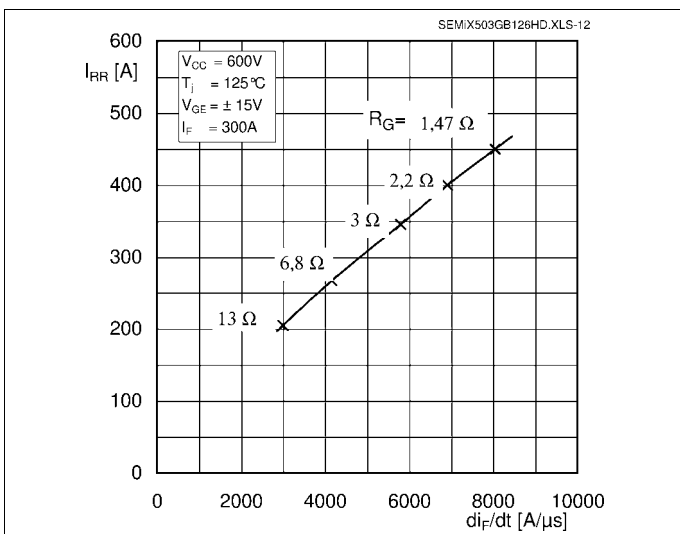


Fig. 11: Typ. CAL diode peak reverse recovery current

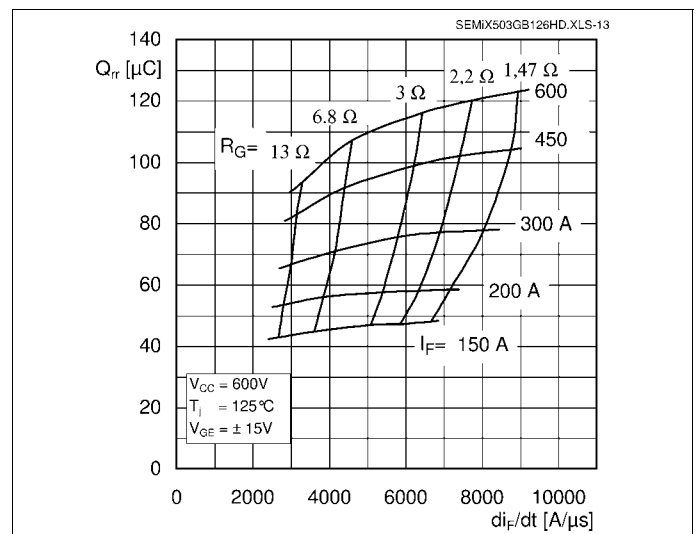
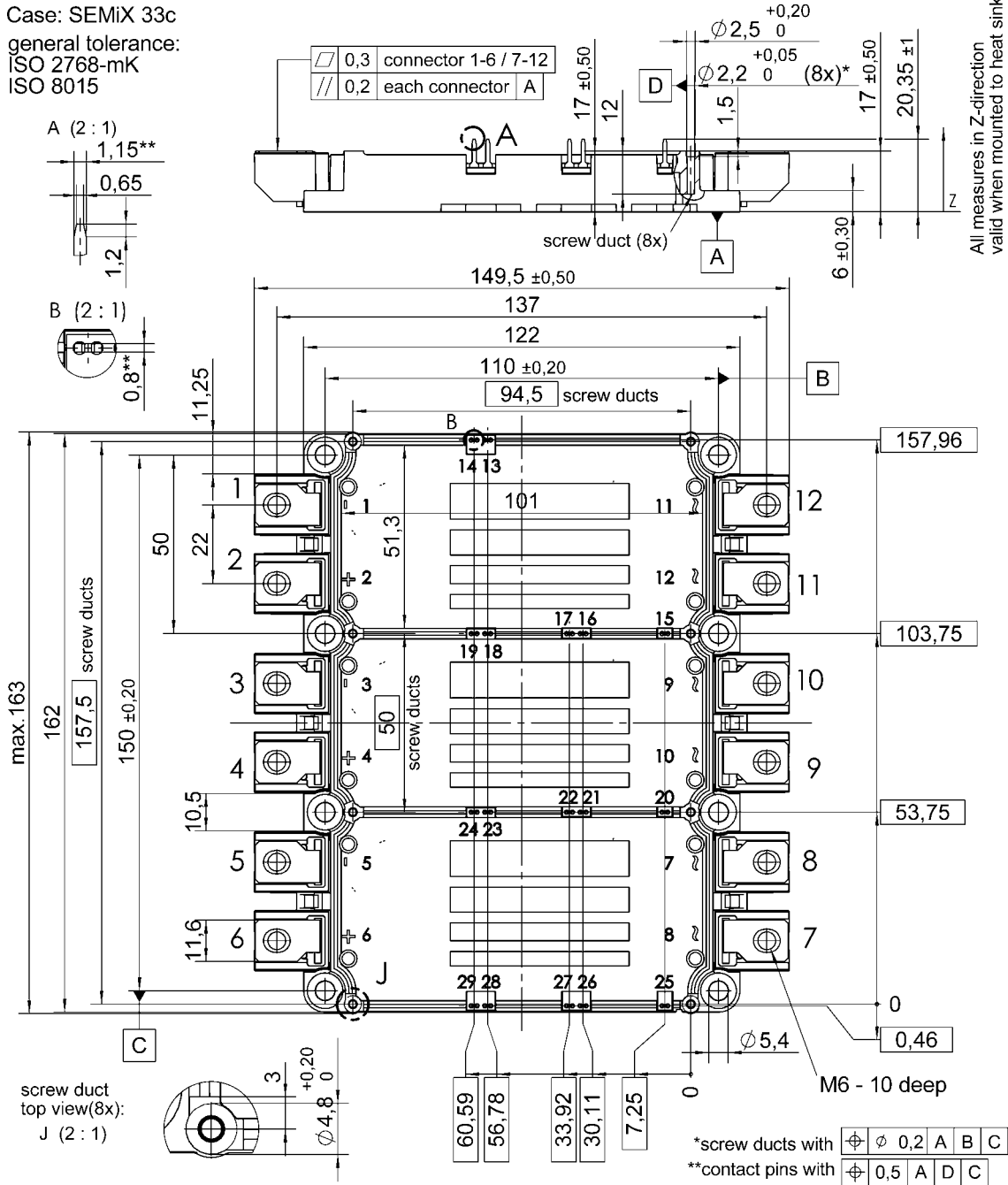


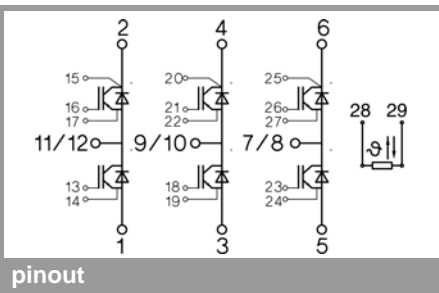
Fig. 12: Typ. CAL diode recovery charge

Case: SEMiX 33c
 general tolerance:
 ISO 2768-mk
 ISO 8015



All measures in Z-direction valid when mounted to heat sink

SEMiX 33c



This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.